

In the Claims:

Please enter the following amended claims 18 and 58:

18. (Twice Amended) A structure comprising:

a substrate having a top surface for receiving a chip;

a printed circuit board attached to a bottom surface of said substrate;

at least one signal via in said substrate;

said at least one signal via providing an electrical connection between a device electrode of said chip and said printed circuit board;

a plurality of separate thermally conductive vias in said substrate, each of said plurality of separate thermally conductive vias being coupled to a heat spreader, said heat spreader being directly attached to said bottom surface of said substrate.

58. (Twice Amended) A structure comprising:

a substrate having a top surface and a bottom surface;

a semiconductor chip attached to said top surface of said substrate;

a heat spreader directly attached to said bottom surface of said substrate;

a first plurality of separate thermally conductive vias in said substrate;

said first plurality of separate thermally conductive vias providing a connection between said semiconductor chip and said heat spreader.